

Preliminary Amendment

Page 3 of 4

Applicant(s): Cobbley et al.

Serial No. Unknown

Filed: Herewith

For: ADHESIVE COMPOSITION FOR USE IN PACKAGING APPLICATIONS

Remarks

Claims 83-92 are new. Claims 15-21 and 83-92 are pending in the present application.

Please enter and consider the specification as amended. The specification is amended herewith to correct a typographical error, in which the name of an inventor in a cited reference was inadvertently misspelled. No new matter has been introduced by this amendment.

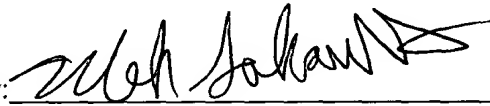
Conclusion

The Examiner is invited to contact Applicants' Representatives at the below-listed telephone number, if there are any questions regarding this Preliminary Amendment or if prosecution of this application may be assisted thereby.

Respectfully submitted,
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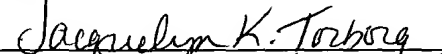
29 Aug 2001
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Name: JACQUELYN K. TORBORG

**APPENDIX A - SPECIFICATION/CLAIM AMENDMENTS
INCLUDING NOTATIONS TO INDICATE CHANGES MADE**

**Serial No.: Unassigned
Docket No.: 150.0072 0103**

Amendments to the following are indicated by underlining what has been added and bracketing what has been deleted. Additionally, all amendments have been shaded.

In the Title

The title has been amended as follows:

[ADHESIVE COMPOSITION AND METHODS FOR USE IN PACKAGING APPLICATIONS] ADHESIVE COMPOSITION FOR USE IN PACKAGING APPLICATIONS

In the Specification

The paragraph beginning at page 15, line 17, has been amended as follows:

In order to increase the thermal stability of an instant setting adhesive composition, a thermal stabilizer can be added to the adhesive composition. Preferably, the thermal stabilizer is a compound selected from the group of an alkyl 2-cyano-2,4-pentadienoate; an alkyl 2-cyano-2,4-hexadienoate; an itaconic anhydride (e.g., U.S. Patent No. 3,984,749 to Konigm); a maleic anhydride (e.g., U.S. Patent No. 3,832,334 to O'Sullivan, et al.); a substituted naphthasultone (e.g., U.S. Patent No. 5,424,343 to Attarwala); a di- α -cyanopentadienoate disiloxane (e.g., U.S. Patent No. 5,386,047 to **[Nakes] Nakos** et al.); a sulfur-containing compound such as a sulfoxide, a sulfonate, a sulfinate, etc. (e.g., U.S. Patent No. 5,328,944 to Attarwala et al.), an aromatic compound substituted with at least three electron withdrawing groups (e.g., U.S. Patent No. 5,288,794 to Attarwala); a bifunctional monomer (e.g., a (meth)acrylic acid ester, an aliphatic polyol, an aromatic polyol, to name a few); an unsaturated ester of 2-cyanoacrylic acid (e.g., U.S. Patent No. 3,142,698 to Benjamin et al., and U.S. Patent No. 3,825,580 to Kato et al.); and mixtures thereof. Other thermal stabilizers can optionally be added to increase the thermal degradation temperature, glass transition temperature or both and can be selected from the group of SiO_2 , Al_2O_3 , AlN , Ag , Ni , Fe , and mixtures thereof.

150.0072 0103